

# Chip Scale Review

## 2018 Editorial Calendar

**(Editorial close date: 11/20/2017)**

**January • February**

\* indicates show distribution

Enabling advanced applications in semiconductor packaging

Challenges and solutions to driving fan-out into high volume

Surface analysis as a blueprint for semiconductor package manufacturing

Laser debonding for WLP

Adhesives for advanced packaging

Automotive sensing

3D heterogeneous integration

3D bump inspection

Improving efficiency in IC testing

Reliability and thermal management

- **SEMI European 3D Summit**  
Dresden, Germany (Jan 22-24)
- **SEMICON Korea**  
Seoul, Korea (Jan 31-Feb 2)
- **SMTA Pan Pac Microelectronics Symposium**  
Waimea, Hawaii (Feb 5-8)
- **2018 FLEX**  
Monterey, CA (Feb 12-15)
- **APEX Expo**  
San Diego, CA (Feb 27-Mar1)
- **ISS Europe**  
Dublin, Ireland, (Mar 4-6)
- **BiTS Workshop\***  
Mesa, AZ (March 4-7)
- **IMAPS DPC\***  
Fountain Hills, AZ (March 5-8)
- **SEMICON China\***  
Shanghai, China (March 14-16)

**Ad Space Close Jan 5 - Ad Materials Close Jan 12**

**(Editorial close date: 1/6)**

**March • April**

\* indicates show distribution

OSATS market update

HD FO-WLP

SiPs for increased functionality

HVM lithography applications

Smart innovations in automotive electronics

Material supply challenges for future devices

MEMS and sensor integration

Advances in failure analysis

Higher performance test solutions

- **SEMICON SE Asia**  
Kuala Lumpur, Malaysia (May 8-10)
- **MEMS & Sensors Technical Congress**  
Stanford, CA (May 10-11)
- **ECTC \***  
San Diego, CA (May 30- June 2)

**Ad Space Close Feb 10 - Materials Close Feb 15**

**(Editorial close date: 3/9)**

**May • June**

\* indicates show distribution

Next-gen IOT solutions

Underfill and encapsulation

Die attach

TSVs

Metrology for stress analysis

Smart burn-in & test sockets

Critical processes for fan-out

Trends in Cu pillar

Innovative IC trends in the China

- **IEEE/SW Test Workshop (SWTW)**  
San Diego, CA (June 3-6)
- **Sensors Expo**  
San Jose, CA (June 26-28)
- **SEMICON West \***  
San Francisco, CA (July 10-12)

**Ad Space Close May 19 - Ad Materials Close May 24**

For ad inquiries: [ads@chipscalereview.com](mailto:ads@chipscalereview.com) - For editorial inquiries [editor@chipscalereview.com](mailto:editor@chipscalereview.com)

Notes: Editorial calendar topics and distribution are subject to change without notice and are contingent on logistics and magazine production.  
Haley Publishing Inc.2017 All rights reserved. Rev:CSR-EC-120517